

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60V	1.6mΩ@10V	318A

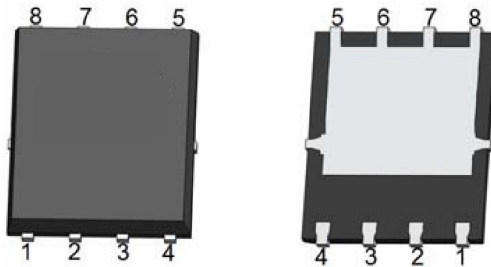
Feature

- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on-resistance $R_{DS(on)}$
- Suffix "-Q1" for AEC-Q101

Application

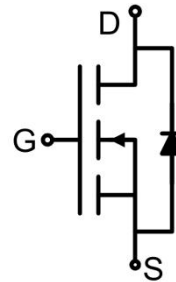
- DC-DC converter
- Ideal for high-frequency switching and synchronous rectification

Package

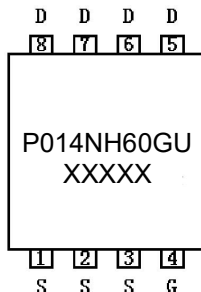


PDFN5*6-8L

Circuit diagram



Marking



Absolute maximum ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	318	A
Continuous Drain Current (T _c =100°C)	I _D (100°C)	200	A
Pulsed Drain Current ¹⁾	I _{DM}	1272	A
Power Dissipation	P _D	280	W
Thermal Resistance,Junction-to-Case	R _{θJC}	0.45	°C/W
Single pulse avalanche energy ⁵⁾	E _{AS}	520	mJ
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_c=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage ³⁾	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V
Drain-source on-resistance ³⁾	R _{DS(on)}	V _{GS} =10V, I _D =20A		1.3	1.6	mΩ
Forward Transconductance ³⁾	g _{FS}	V _{DS} =10V, I _D =20A		60		S
Dynamic characteristics⁴⁾						
Input Capacitance	C _{iSS}	V _{DS} =30V, V _{GS} =0V, f =1MHz		5478		pF
Output Capacitance	C _{oss}			2012		
Reverse Transfer Capacitance	C _{rSS}			178		
Total Gate Charge	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =20A		97.7		nC
Gate-Source Charge	Q _{gs}			29.7		
Gate-Drain Charge	Q _{gd}			31.3		
Turn-on delay time	t _{d(on)}	V _{DD} =30V, V _{GS} =10V, I _D =20A, R _G =4.7Ω		24		nS
Turn-on rise time	t _r			21		
Turn-off delay time	t _{d(off)}			45		
Turn-off fall time	t _f			18		
Source-Drain Diode characteristics						
Diode Forward Current ²⁾	I _S				318	A
Diode Forward voltage ³⁾	V _{SD}	V _{GS} =0V, I _S =20A			1.2	V
Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =40A, di/dt =100A/μs ³⁾		60		nS
Reverse Recovery Charge	Q _{rr}			80		nC

Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2) Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3) Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- 4) Guaranteed by design, not subject to production
- 5) EAS condition : T_J=25°C, V_{DD}=30V, V_G=10V, L=0.5mH, R_G=25Ω

Typical Characteristics

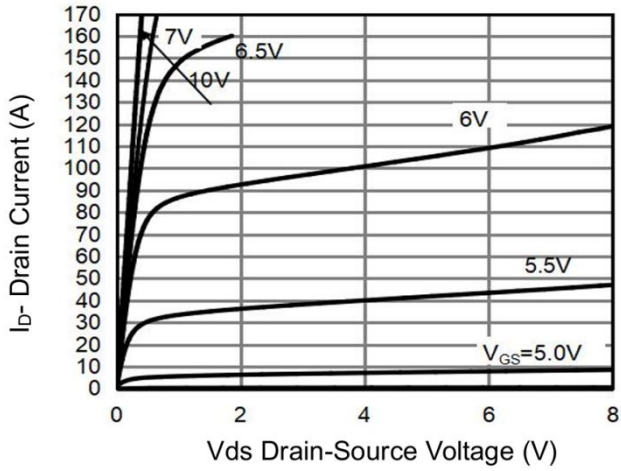


Figure 1 Output Characteristics

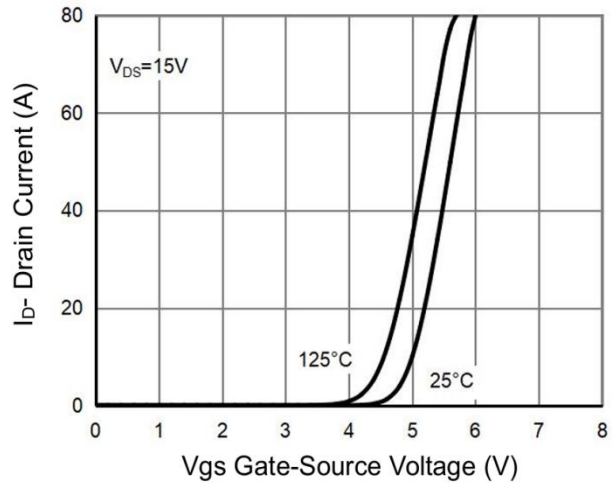


Figure 2 Transfer Characteristics

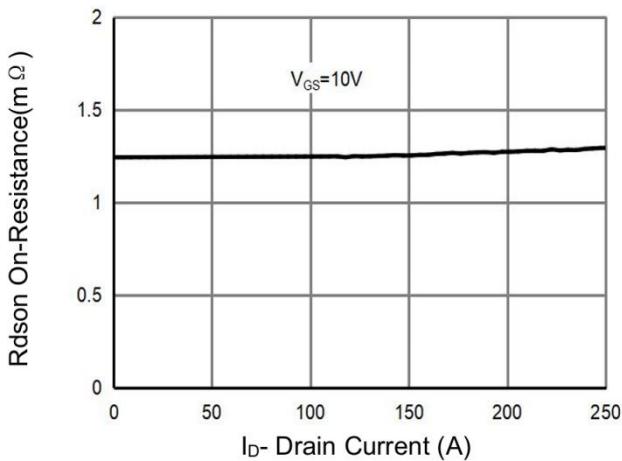


Figure 3 Rdson- Drain Current

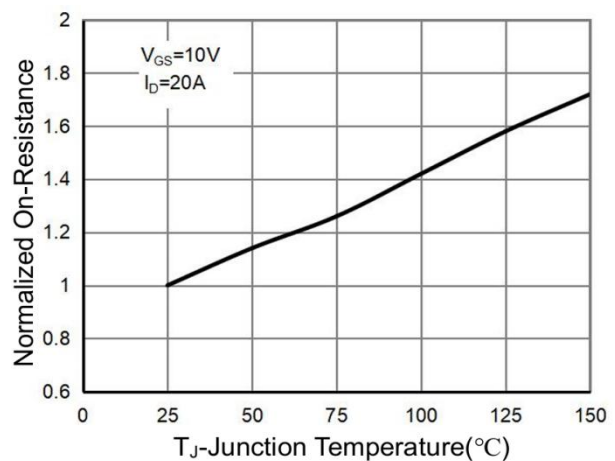


Figure 4 Rdson-Junction Temperature

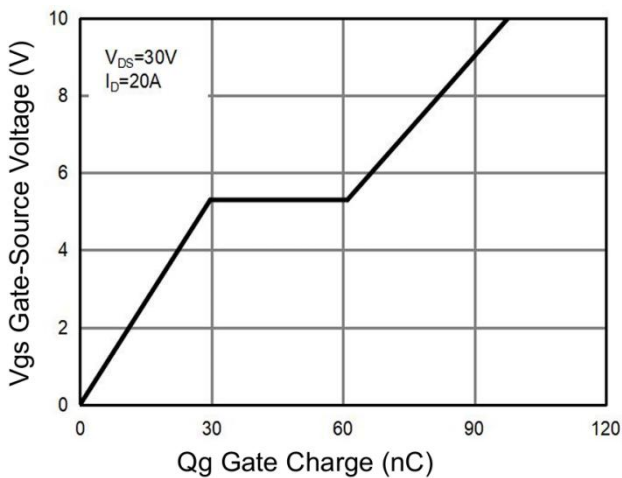


Figure 5 Gate Charge

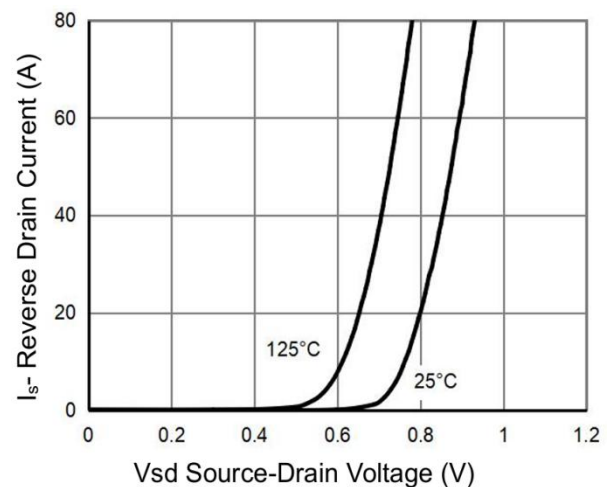


Figure 6 Source- Drain Diode Forward

Typical Characteristics

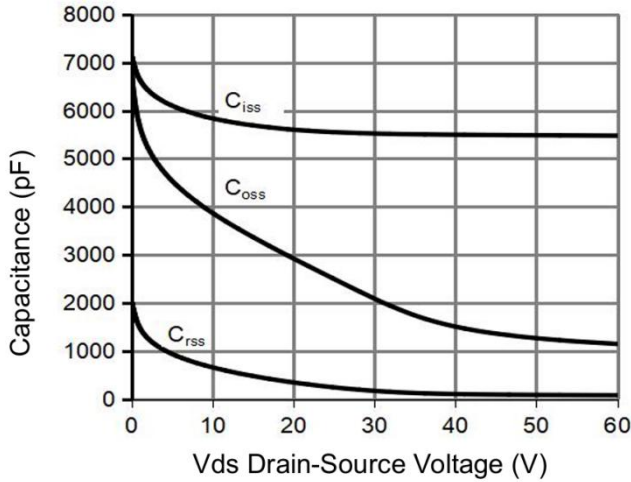


Figure 7 Capacitance vs Vds

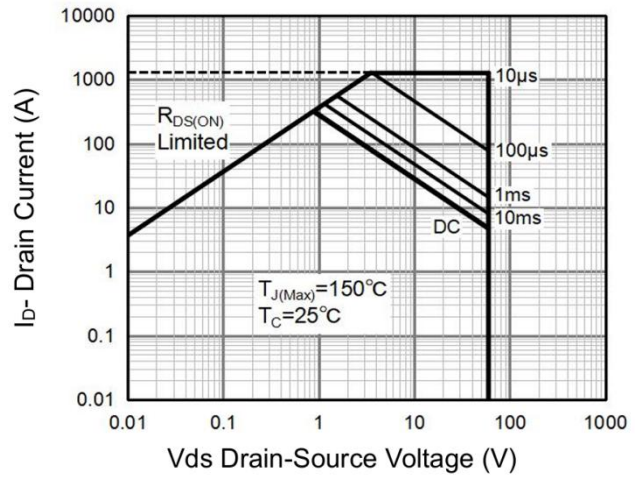


Figure 8 Safe Operation Area

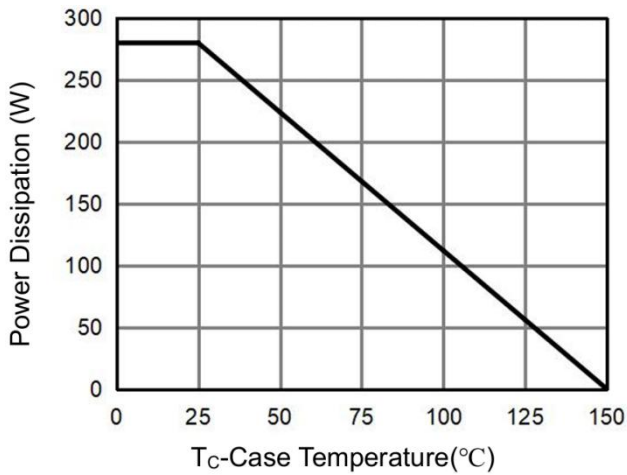


Figure 9 Power De-rating

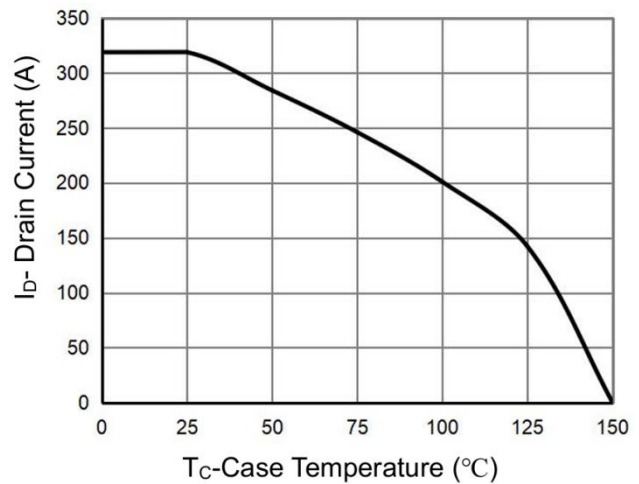


Figure 10 Current De-rating

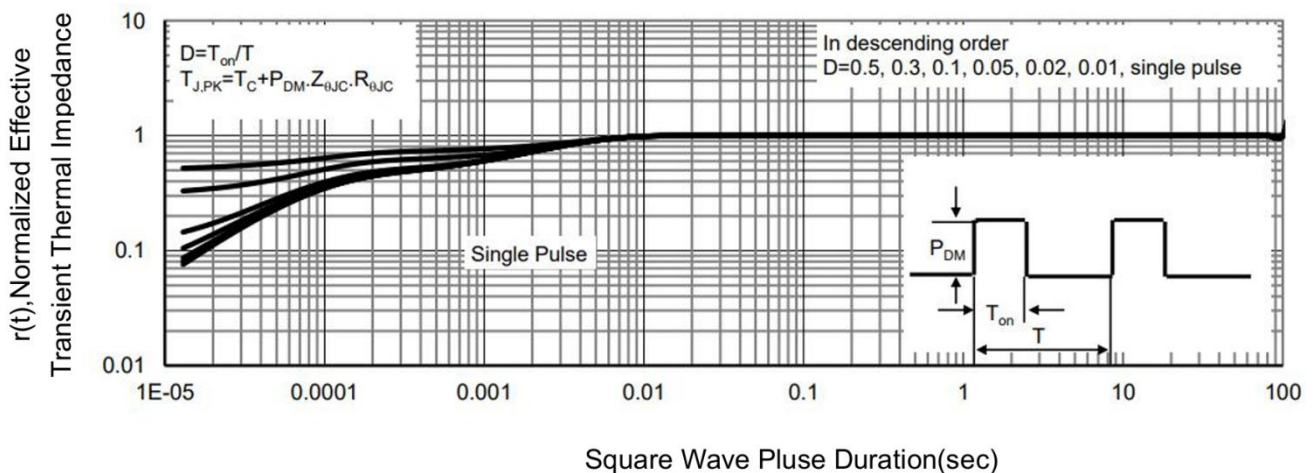
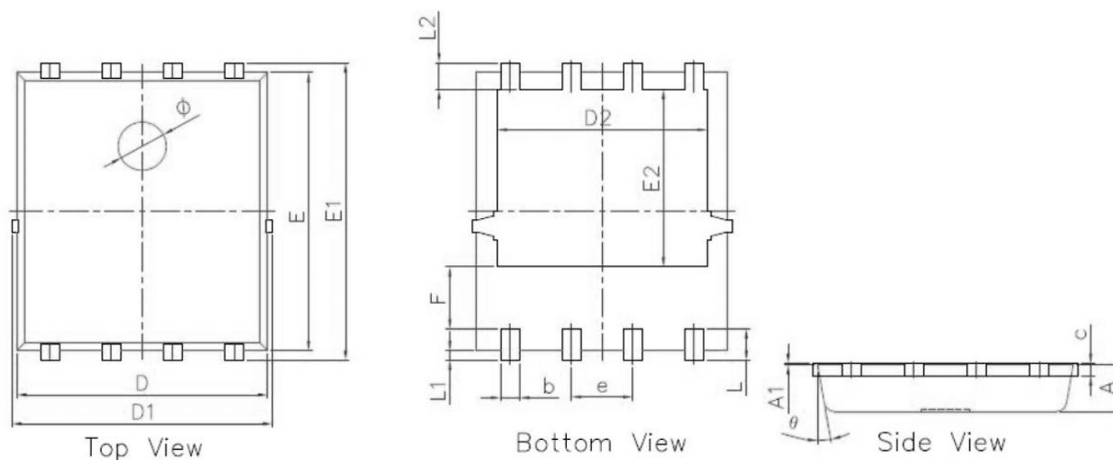


Figure 11 Normalized Maximum Transient Thermal Impedance

PDFN5*6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A1	0.000	0.050	0.000	0.002
b	0.350	0.500	0.014	0.020
C	0.200	0.300	0.008	0.012
D	5.100	5.300	0.201	0.209
D1	5.100	5.500	0.201	0.217
D2	4.250	4.450	0.167	0.175
E	5.700	5.800	0.224	0.228
E1	6.000	6.300	0.236	0.248
E2	3.570	3.770	0.141	0.148
e	1.270 BSC.		0.050 BSC.	
F	1.180	1.380	0.046	0.054
L	0.550	0.750	0.022	0.030
L1	0.150	0.250	0.006	0.010
L2	0.450	0.650	0.018	0.026
Φ	0.900	1.100	0°	12°
θ	8°	12°	8°	12°